Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]

<table>
<thead>
<tr>
<th>Model Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>HP ProDesk 400 G5 MT Business PC</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>3</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Delta EPA90 310W</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner Include the cartridges, print heads, tubes, vent chambers, and service stations.

Components and waste containing asbestos

Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

### 2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>Micro shear</td>
<td>170II</td>
</tr>
<tr>
<td>Screwdriver</td>
<td>PH1</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Loose the screw and remove access panel.(see Figure 1 below)
2. Disconnect ODD/HDD power cable and SATA cable from ODD/HDD.(see Figure 2-5 below)
3. Remove the driver cage from chassis.(see Figure 6 below)
4. Remove ODD/HDD from driver cage.(see Figure 7-10 below)
5. Disconnect all cables from the MB.(see Figure 11-18 below)
6. Remove the heatsink from MB.(see Figure 19 below)
7. Separate the fan from CPU heatsink. (see Figure 20-21 below)
8. Remove the Memory card from the MB.(see Figure 22 below)
9. Remove the CPU from the MB.(see Figure 23-24 below)
10. Remove the battery from the MB .(see Figure 25 below)
11. Remove M/B from chassis.(see Figure 26-28 below)
12. Remove Speaker/system fan from chassis.(see Figure 29-30 below)
13. Remove PSU from chassis.(see Figure 31-34 below)
14. Separate PSU cover/fan and remove the Electrolytic Capacitors.(see Figure 35-42 below)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1: Loose thumb screw and remove access panel

Figure 2: Disconnect ODD power cable from ODD

Figure 3: Disconnect SATA cable from ODD

Figure 4: Disconnect HDD Power cable from HDD

Figure 5: Disconnect SATA cable from HDD

Figure 6: Remove the driver cage from chassis

PSG instructions for this template are available at EL-MF877-01
Figure 7 Press the ODD’s latch on ODD cage

Figure 8 Remove the ODD from ODD cage

Figure 9 Use T-15 screwdriver to loose the screws of HDD from cage

Figure 10 Remove the HDD from HDD cage

Figure 11 Disconnect SATA cable from the MB

Figure 12 Disconnect ODD/HDD PSU cables from the MB

PSG instructions for this template are available at EL-MF877-01
Figure 13 Disconnect PSU P1 cable from the MB

Figure 14 Disconnect PSU P2 cable from the MB

Figure 15 Disconnect CPU P3 cable from the MB

Figure 16 Disconnect Speaker cable from the MB

Figure 17 Disconnect system fan cable from the MB

Figure 18 Disconnect heat sink fan cable from MB
Figure 19 Use T-15 screwdriver to loosen the screws and remove the heat sink

Figure 20 Use PH1 screwdriver to loosen the screws and remove the fan

Figure 21 Separate the fan from CPU heat sink

Figure 22 Remove the Memory card from the board

Figure 23 Rotate the handle and open it up

Figure 24 Remove the CPU from the board
Figure 25 Remove the battery from the system board

Figure 26 Use T-15 screwdriver to loose the screws of MB from board

Figure 27 Remove front panel from chassis

Figure 28 Remove MB from chassis

Figure 29 Use T-15 screwdriver to loose the screws of speaker and remove it

Figure 30 Use PH1 screwdriver to loose the screws of system fan and remove it
Figure 31 Use micro shear 170II to cut the cable ties from chassis front wall

Figure 2 Use T-15 screwdriver to loose the screws of PSU

Figure 33 Press the PSU’s latch on chassis

Figure 34 Remove the PSU from chassis

Figure 35 Remove cover screw

Figure 36 Remove cover screw
Figure 37 Remove cover screw

Figure 38 Cut the cable tie

Figure 39 Disconnect input wire connector

Figure 40 Disconnect fan wire connector

Figure 41 Remove 4 PCB screws

Figure 42 Remove Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height

PSG instructions for this template are available at EL-MF877-01